1 Supplementary Information

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3 Highly transparent, intrinsically stretchable, photo-patternable, and vacuum-deposited

- 4 electrodes for wearable sensors and displays
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11 This PDF file includes:

- 12 Supplementary Figures 1–20
- 13 Supplementary Tables 1-2
- 14 Legend for Supplementary Video 1
- 15

16 Other Supplementary Materials for this manuscript include the following:

17 Supplementary Video 1

1 Supplementary Figures



Supplementary Fig. 1 | Tape peeling test showing the robustness of Au nanomembrane 3 on SEBS against mechanical abrasion. a, The Au nanomembrane on SEBS shows high 4 resistance against tape peeling, while the surface remains nearly unbroken after tape peeling, 5 due to its interpenetrating structure. b, The conventional Au on PDMS has weak bonding 6 between AuNPs and substrate, thus the Au was easily peeled off by tape, leaving transparent 7 substrate. c, Relative resistance changes of the Au nanomembrane on SEBS under tape peeling 8 compared to the conventional Au on PDMS, which demonstrate the mechanical and electrical 9 robustness of the Au nanomembrane on SEBS. 10



Supplementary Fig. 2 | TOF-SIMS analysis of AuNPs diffused within the SEBS elastomer 2

matrix at different deposition rates. a-c, Au dispersion profiles at deposition rate of 5.0 Å s⁻¹ 3

(a), 0.5 Å s⁻¹ (b), and 0.1 Å s⁻¹ (c). **d**, The Au⁻-to-C⁻ peak ratio. Au⁻ (yellow) and C⁻ (blue) were selected as the characteristic group during sputtering to evaluate the nano-dispersion of the 5

AuNPs to SEBS elastomer matrix along the film thickness direction. 6

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2 Supplementary Fig. 3 | Normalized resistance changes of Au nanomembrane electrodes
3 under strain, displayed on a logarithmic scale. a,b, Measurements across strain ranges of

4 1.0–6.0 (a) and 1.0–1.5 (b). The sample has a width of 1 cm and a length of 3 mm.





- 2 Supplementary Fig. 4 | Transmittance of the T-iSPV electrode compared to that of the
- 3 SEBS-Au bulk electrode.



- 2 Supplementary Fig. 5 | OM images show the as-fabricated mesh electrodes after the wet
- 3 etching process (a) and the lift-off process (b).



- 2 Supplementary Fig. 6 | The sheet resistance distributions of the T-iSPV. Histograms
- 3 showing the sheet resistance for 48 individual electrodes.



- 2 Supplementary Fig. 7 | OM images of patterned PR (a) and Au nanomembrane (b) on
- **SEBS.**



- 2 Supplementary Fig. 8 | Transmittance of the T-iSPV electrode as determined by the ratio
- 3 of pitch to line width.



Supplementary Fig. 9 | Photographs and transmittance of the wet-etched control
 electrode and the T-iSPV electrode.



Supplementary Fig. 10 | TOF-SIMS analysis of AuNPs diffused within the SEBS elastomer matrix. a–d, Au dispersion profiles in the control line mesh region (a) and its adjacent blank region with residual AuNPs (c), compared to the T-iSPV line mesh region (b) and its blank region without AuNP accumulation at the surface (d). e, The Au⁻-to-C⁻ peak ratio. Au⁻ (yellow) and C⁻ (blue) were selected as the characteristic group during sputtering to evaluate the nano-dispersion of the AuNPs to SEBS elastomer matrix along the film thickness direction.



Supplementary Fig. 11 | Photographs of T-iSPV on the forearm skin. The blue dashed boxes on the right highlight the outer boundary of the electrode, while the red arrows indicate the directions of compressive and tensile strains. The red dashed box at the top left corresponds to the field of view shown in the bottom left. After undergoing compressive and tensile strains, the T-iSPV remained conductive.



- 2 Supplementary Fig. 12 | OM and AFM images of the T-iSPV line mesh region and its
- 3 adjacent blank region, before and after stretching. RMS, root mean square roughness.



2 Supplementary Fig. 13 | Transmittance changes in T-iSPV electrodes under strain.



- 2 Supplementary Fig. 14 | Resistance changes in the T-iSPV electrodes during stretching
- 3 cycles at 30% strain. The inset shows magnified resistance changes over 20 stretching cycles.



2 Supplementary Fig. 15 | Impedance of T-iSPV.





Supplementary Fig. 16 | EIS impedance measurement between the T-iSPV and the skin 3 surface. a, Schematic illustration of the EIS measurement setup. REF, reference electrode; CE, 4 counter electrode; WE, working electrode; WS, working sense electrode. b, Impedance 5 measured on the forearm in contact with the T-iSPV in dry state for normal skin condition 6 (black) and wet state for skin surface moistened with 1X PBS to mimic sweat exposure (blue). 7 c, EIS fitting parameters, from the equivalent circuit diagram of the contact impedance, 8 including the T-iSPV-skin interface resistance (left) and the T-iSPV-skin interface capacitance 9 (right). Data are expressed as the mean \pm s.d. (n = 5 for independent samples). Statistical 10 significance and P values were determined by two-sided unpaired t-tests; ns, not significant. 11 [Illustration in (a) was created with BioRender.com] 12



2 Supplementary Fig. 17 | Schematic illustration of fabrication process of sECD.

3 This revision more precisely describes the vertical stacking and bonding process used to4 assemble the sECD. We hope this explanation and the added visual aid address the reviewer's

5 concerns thoroughly.





Supplementary Fig. 18 | Resistance changes measured from tactile sensors upon finger touch. a, Sensor configuration based on a short-circuit design, exhibiting negligible resistance variation due to a direct conductive path. b, Open-circuit sensor configuration with a parallel resistor, showing a distinct resistance change upon touch, enabling reliable tactile signal detection.



- 2 Supplementary Fig. 19 | Matlab code applied for TIBS.

1	const int analogDint - AF:	62	// Reset PWM values
1	int testile of	63	pwm1_H = 0; pwm1_L = 0;
2	int tactile = 0;	64	pwm4_H = 0; pwm4_L = 0;
3	int tactilevalue = 0;	65	
4	int previousTactilevalue = 0;	66	
5		67 V	if (powerChanged && power && (millis() - powerChangeTime < 1000)) {
6	// PWM pins	68	pwm1_H = 250;
7	const int ecdPin1_High = 3;	69	<pre>state1 = 1;</pre>
8	const int ecdPin1_Low = 5;	70	
9	<pre>const int ecdPin4_High = 7;</pre>	71	// Power off: pwm1 L = 300 for 1 second
10	<pre>const int ecdPin4_Low = 9;</pre>	72 ~	else if (powerChanged && !power && (millis() - powerChangeTime < 1000)) {
11		73	pwm1 L = 250;
12	bool power = true;	74	state1 = 0:
13	<pre>bool lastPower = true;</pre>	75	
14		76 🗸	else {
15	String Rx = "";	77	// Maintain state after 1 second
16	String lastRx = "";	78	powerChanged = false:
17		79 🗸	if (nower) {
18	<pre>int pwm1_H = 0, pwm1_L = 0;</pre>	80	state1 = 1:
19	int pwm4_H = 0, pwm4_L = 0;	81 🗸	} else {
20	<pre>int state1 = 0, state4 = 0;</pre>	82	state1 = 0:
21		83	}
22	// Timing variables	84	
23	unsigned long powerChangeTime = 0;	85	
24	unsigned long rxChangeTime = 0;	86	// Handle Rx command when power is ON
25	<pre>bool powerChanged = false;</pre>	87 ~	if (nower) {
26	<pre>bool rxChanged = false;</pre>	88 ¥	if (ryChanged && (millis() - ryChangeTime < 1000)) {
27		89 1	if (Ry == "1") {
28 🗸	<pre>void setup() {</pre>	90	num4 = 150:
29	Serial.begin(115200);	91	state4 = 0:
30	Serial.setTimeout(50);	92 ~	$\beta = \beta = \beta = 2^{\circ} \beta$
31		03	$n_{\text{um}} H = 150$
32	<pre>pinMode(ecdPin1_High, OUTPUT);</pre>	04	state4 = 1.
33	<pre>pinMode(ecdPin1_Low, OUTPUT);</pre>	95	l l
34	<pre>pinMode(ecdPin4_High, OUTPUT);</pre>	95 ¥	<pre>l else if (ryChanged && (millis() - ryChangeTime >= 1000)) {</pre>
35	<pre>pinMode(ecdPin4_Low, OUTPUT);</pre>	07	rychanged = false:
36		09	// Maintain stated based on By but paset DLM
37		00	if $(P_{Y} = "1")$ stated = 0.
38 🗸	void loop() {	100	also if $(P_{Y} = - 2^{\circ})$ stated = 1.
39	// Read sensor and calculate value	101	l l l l l l l l l l l l l l l l l l l
40	<pre>tactile = analogRead(analogPin1);</pre>	102	
41	<pre>tactileValue = (tactile - 400) * 5 + 1600;</pre>	102	stated = 0: // Earce OFF if newer is off negandlass of Py
42		103	state4 = 0, // Force OFF 11 power 15 011, regardless of KA
43	// Toggle power state	105	
44 🗸	if (previousTactileValue > 0 && tactileValue <= 0) {	105	// DLM output
45	power = !power;	100	analogunite(ecdDint High promt H):
46	powerChanged = true;	100	analogwrite(ecurini_nigh, pwmi_n),
47	<pre>powerChangeTime = millis();</pre>	100	analoginite(ecdPin4_Low, pwm1_L),
48		110	analogwrite(ecurin4_nigh, pwm4_n),
49	<pre>previousTactileValue = tactileValue;</pre>	110	analogwiite(ecurinii_cow, pwm+_c),
50	New AND CALMER WAS CALMED TO CALMERS	111	
51	// Receive command	112	Senial point("Data "):
52	<pre>String receivedData = Serial.readString();</pre>	114	Serial print(tactilaValue):
53 🗸	if (receivedData.length() > 0) {	115	Serial print(" ")
54	<pre>String newRx = receivedData.substring(0, 1);</pre>	115	Senial point(state1):
55 🗸	if (newRx != Rx) {	117	Senial anint(""):
56	Rx = newRx;	110	Senial anintln(state():
57	rxChanged = true;	110	Ser Ior. printen (state4),
58	<pre>rxChangeTime = millis();</pre>	120	lastDowen - nowen:
59		120	lactor = power,
		122	
		122	delay(5):
		124	
		124	

- 2 Supplementary Fig. 20 | Arduino code applied for TIBS.

1 Supplementary Tables

		T₋iSPV	ITO ^{1,2,4}	Cu metal mesh ³	Graphene ^{4,5,6}	AgNW ^{7,8}	CNT ^{9,10,11,12}	
	Intrinsic stretchability	50%	≈3%	Х	≈6%	100%	80%	
	Sheet resistance ($\Omega \square^{-1}$)	83.7	250, 30	0.22	350-1200, 125	13, 11.01	59-110, ~560	
	Optical transmittance (@ 550nm)	77.17	≈ 90%	83%	~ 97.4%	85%, 90.6%	71-80%, 75%	
	Microfabrication compatibility	0	0	0	0	Х	Х	
	Substrate thickness (Skin conformity)	≈5 µm	200 µm	-	25 µm, 188 µm	150 µm	230 µm	
	Uniformity	0	0	0	Х	Х	Х	
2	Biocompatibility	0	Х	Х	Х	Х	Х	

3 Supplementary Table 1 | Comparison of T-iSPV with transparent conductive electrodes

Year	Material strategy	Stretchability (%)	Transparency (%)	Sheet Resistance (Ω/sq)	Cyclic Durability	Line width (µm)	Substrate	Fabrication method	Mesh structure	Application	Reference
2025	Ag grid/ Ag Nanowire	flexible	67.9	9	5,000 (bending)	15	NOA63	Photolithography/ Bar-coating	Square	OLED	[13]
2025	Ag metal mesh	flexible	73.1	1.52	1,000 (bending)	-	PET	Nanosphere lithography	circle	Heater, EMI sheilding	[14]
2025	Cu metal mesh	60%	83	0.22	20,000 (bending)	4.3	PDMS	Photolithography (Transfer)	Serpentine	Film heater	[15]
2025	Ag grid	100%	84.8	29.9	5,000 (50% stretching)	35-50	PDMS	Inkjet printing	Serpentine	Touch panel	[16]
2024	Liquid metal/ Cu metal mesh	800%	78.9 – 95.1	1.52 - 7.76	10,000 (300% stretching)	35	SEBS	Laser ablation	Serpentine	Haptic interface/Heater	[17]
2024	Cu metal mesh	30%	85.8	0.18	1,000 (bending)	1-2	PDMS	Self-forming crackle template method	Irregular	Heater	[18]
This work	Au mesh	50%	77.17	83.7	1,000 (30% stretching)	10	Ultrathin SEBS (5 µm)	In-situ vacuum- deposition, phtolithography	Square (Intrinsically stretchable)	Electrophysiological electrode, ECD, Tactile senor, Integrated display system	

2 Supplementary Table 2 | Comparison of T-iSPV with state-of-the-art literature on metal

3 mesh-based deformable transparent electrodes.

1 Supplementary Video

2

3 Supplementary Video 1. Real-time demonstration of the integrated bioelectronics system.

A fully assembled wearable platform integrating T-iSPV-based ECG electrodes, a stretchable
electrochromic display (sECD), and a tactile sensor was mounted on human skin. Upon tactile
stimulation, the system activates in real time, toggling the sECD to visually indicate operation.
Concurrently, ECG signals are acquired via the T-iSPV electrode, processed through the data
acquisition module, and used to control the second sECD, which turned on when the measured
heart rate falls below a predefined threshold. This demonstration validates the seamless
integration and functional responsiveness of the system under dynamic conditions.

1 Supplementary References

- 2 1. H. K. Yu, S. Kim, B. Koo, G. H. Jung, B. Lee, J. Ham and J.-L. Lee, *Nanoscale*, 2012, 4,
 3 6831-6834.
- 4 2. K. Sakamoto, H. Kuwae, N. Kobayashi, A. Nobori, S. Shoji and J. Mizuno, *Scientific*5 reports, 2018, 8, 2825.
- 6 3. Z. Nie, W. Yan, X. Han, H. Yu, Y. Zhang, M. Tian, X. Zhang, Y. Xiong, P. Cao and G.
 7 Zhang, *Composites Part B: Engineering*, 2025, 289, 111934.
- 8 4. X. Li, Y. Zhu, W. Cai, M. Borysiak, B. Han, D. Chen, R. D. Piner, L. Colombo and R. S.
 9 Ruoff, *Nano letters*, 2009, 9, 4359-4363.
- 5. S. Bae, H. Kim, Y. Lee, X. Xu, J.-S. Park, Y. Zheng, J. Balakrishnan, T. Lei, H. Ri Kim and
 Y. I. Song, *Nature nanotechnology*, 2010, 5, 574-578.
- 6. S. De, T. M. Higgins, P. E. Lyons, E. M. Doherty, P. N. Nirmalraj, W. J. Blau, J. J. Boland
 and J. N. Coleman, *ACS nano*, 2009, **3**, 1767-1774.
- 7. D. Kuzum, H. Takano, E. Shim, J. C. Reed, H. Juul, A. G. Richardson, J. De Vries, H. Bink,
 M. A. Dichter and T. H. Lucas, *Nature communications*, 2014, 5, 5259.
- 16 8. C.-J. Lee, K. H. Park, C. J. Han, M. S. Oh, B. You, Y.-S. Kim and J.-W. Kim, *Scientific*17 *reports*, 2017, 7, 7959.
- 9. E. M. Doherty, S. De, P. E. Lyons, A. Shmeliov, P. N. Nirmalraj, V. Scardaci, J. Joimel, W.
 J. Blau, J. J. Boland and J. N. Coleman, *Carbon*, 2009, 47, 2466-2473.
- 20 10. B. S. Shim, J. Zhu, E. Jan, K. Critchley and N. A. Kotov, Acs Nano, 2010, 4, 3725-3734.
- 21 11. J. W. Jo, J. W. Jung, J. U. Lee and W. H. Jo, Acs Nano, 2010, 4, 5382-5388.
- 12. A. Vohra, P. Imin, M. Imit, R. S. Carmichael, J. S. Meena, A. Adronov and T. B.
 Carmichael, *RSC Advances*, 2016, 6, 29254-29263.
- 24 13. H. Yang, Y. Bi, S. Wang, C. Wang, H. Wang, G. Ye and J. Feng, Photonics, 2025, 12, 272.
- 14. M. Zarei, K. Mohammadi, A. A Mahmood, M. Li and P. W. Leu, ACS Appl. Electron.
 Mater., 2025, 7, 4266–4278.
- 27 15. Z. Nie, W. Yan, X. Han, H. Yu, Y. Zhang, M. Tian, X. Zhang, Y. Xiong, P. Cao and G.

- 1 Zhang, Composites Part B: Engineering, 2025, 289, 111934.
- 2 16. S. Yang, Y. Cao, K. Han, J. Guo, P. Zheng, L. Wang, T. Cheng, Y. Zhang, W. Lai, Nano
 3 Energy, 2025, 139, 110942.
- 4 17. C. Yang, X. Ma, X. Zhou, Y. Lin, W. Huang, X. Chen, Q. Wang, Q. Lu, Y. Xu, X. Ning
 5 and D. Kong, ACS Materials Lett., 2024, 6, 3124–3132.
- 6 18. Z. Chen, S. Yang, J. Huang, Y. Gu, W. Huang, S. Liu, Z. Lin, Z. Zeng, Y. Hu, Z. Chen, B.
- 7 Yang and X. Gui, Nano-Micro Lett., 2024, 16.